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A message from our chairman and CEO

“Sustainability” is a multifaceted concept. It represents a spirit of enduring enterprise that transcends time; it requires companies to innovate and create value in a changing world; and it inspires us to wisely utilize resources and cherish our one and only Earth, becoming the pillar of sustainable development in human society.

In 2023, several significant events propelled Winbond to make further progress on the path towards sustainability. At the beginning of the year, the drought in Taiwan led to the creation of our “Water Efficiency Policy.” To achieve net-zero by 2050, we explored renewable energy investment and procurement; and led the way for our supply chain partners to accelerate our progress towards net-zero. The release of Open AI’s GPT4.0 injected new vitality into creating value with AI. Geopolitical conflicts accelerated our adoption of localized layouts, implementing globalization strategies.

To improve management quality and align with international standards, Winbond began ISO 46001 water efficiency management systems certification in the second half of 2023. Based on the vision of “being a hidden champion in providing sustainable semiconductors to enrich human life,” we established the following water efficiency policy:

- Engage everyone in water conservation to enhance awareness of water resource management.
- Prioritize water-saving designs and continuously strive to enhance water resource efficiency.
- Recycle and reuse water resources to ensure the attainment of the water efficiency goals.
- Comply with government regulations and conduct regular reviews of water resource management.

From the initial construction of our CTSP Fab in 2005, the concept of recycling and circulation was incorporated into the design, utilizing dedicated piping systems, real-time water quality monitoring, and the establishment of recycling treatment systems. In addition, the Kaohsiung Fab enhanced water resource recovery through a newly designed process. Winbond also engaged in water-saving technologies exchange with Green Energy and Environment Research Laboratories of the Industrial Technology Research Institute(ITRI), organizing industry tours to share achievements with the industry. In 2023, a total of 6 water-saving projects were introduced, resulting in an annual water saving of up to 390,000 metric tons (approximately 2.4% of the plant's annual water usage), while the overall plant recovery rate increased by 1.7% (from 80.5% to 82.2%).

Due to Taiwan’s limited land and dense population, investing in renewable energy presents a great challenge. Therefore, the management team actively seeks and discusses every opportunity to acquire renewable energy. With over two years of experience, our confidence in transitioning to 100% renewable energy has increased. As electricity usage contributes significantly to Winbond’s carbon emissions, adopting renewable energy can make an important contribution to Winbond’s goal of achieving net-zero emissions.

In 2024, we established a paid volunteer leave policy to encourage employees to participate in social and environmental improvement activities. According to this policy, employees can apply for volunteer leave during working hours to engage in volunteer work, support charitable organizations, and participate in community service or environmental protection activities. This not only helps employee to develop a sense of social engagement and well-being but also reflects our firm commitment to sustainability and community contribution. We will continue to promote this policy to support our employee in participating in meaningful volunteer work, while fostering a more sustainable future.

Our Board of Directors leads Winbond’s sustainable strategy to promote sustainable development. The board has established an ESG Committee, composed of the chairman and independent directors, to jointly formulate a sustainability vision, considering the carbon footprint as a key indicator, and to promote value creation in innovation. We strive to make every employee a sustainable ambassador and jointly cultivate a sustainable culture. In addition, the Risk Management Committee regularly assesses risks and opportunities.

We actively promote for a diverse, equal, and inclusive work environment (DEI) to attract global talent. A Senior Executive Development Committee has been established strengthening talent development and succession planning, while expanding the board’s supervisory functions to establishes a more robust corporate governance framework.

Looking forward, in the development of globalization and localization, the new chapter of corporate social responsibility will encompass activities that integrate and interact with different countries and cultures. I look forward to joining hands with many friends and colleagues to build a beautiful home and fulfill our responsibility to protect our beautiful Earth.



Arthur Yu-Cheng Chiao
Chairman and CEO

A message from our President

2023 was a year filled with challenges and opportunities for Winbond. Despite the ongoing global political and economic turmoil, the increasing severity of climate change, and a complex operating environment, Winbond is keenly aware that the transition to net-zero has become the core issue of sustainability for businesses worldwide. We rely on our expertise in semiconductor process technology and manufacturing services, strict quality management, and product innovation as the solid foundation for sustainability. By internalizing ESG as part of our competitiveness and through clear policies, goals, and concrete actions, we collaborate with stakeholders to implement the company's five main directions for ESG, supporting global sustainability actions.

陳沛銘

James Pei-Ming Chen
President



E

Combining core competencies, innovative technology, and sustainable energy-saving and carbon reduction goals, by implementing energy and carbon emission reduction measures, process efficiency improvements, green product design, and digitization of information systems, we build a long-term sustainable win-win relationships with our customers and supply chain.

At the product design stage, Winbond focuses on incorporating green concepts such as "low-carbon materials," "energy-saving and low-energy consumption," and "smaller form factor and lower pin counts." This approach aligns with international trends and the needs of stakeholders and customers, aiming to minimize environmental impact in product development.

Leveraging DRAM and Flash memory process technology, we have been deep involved in in the KGD (Known Good Die) field and offer SiP (System in Package) multi-chip packaging solutions to reduce packaging materials and chip sizes. We introduced a new generation of low-capacity 3V Serial NOR RV series and 1.2V Hyper-RAM products, which reduced carbon emissions by over 30% compared to previous generations. We also developed flash memory products that support Low-Temperature Soldering (LTS) processes, enabling customers to achieve energy-saving innovations, thereby reducing greenhouse gas (GHG) emissions and creating energy-saving and carbon-reducing end products.

In addressing supply chain sustainability issues, Winbond collaborates with its supply chain partners to established a green semiconductor supply, jointly exploring carbon reduction opportunities. In 2023, Winbond joined Industrial Development Administration of MOEA's post-pandemic low-carbon transformation subsidy program, collaborating with 13 suppliers and outsourcers to formulate carbon reduction plans, to benefit the secondary industry supply chain with carbon reduction progress. As international regulations on net-zero carbon reduction become stricter, we connect internal systems and data through digital tools, applying them to office collaboration and production operations, gradually improving the Company and suppliers' carbon inventory, carbon footprint information, and internal carbon accounting systems. We also utilize AI applications to increase corporate resilience in response to the dynamic semiconductor industry.

In green technology production, Winbond also focuses on renewable energy, water management, water and waste recycling, and GHG emissions reduction as key performance indicators and global actions, dedicated to minimizing environmental externalities. We replaced energy-saving equipment and installed exhaust gas treatment equipment, carried out energy-saving projects, and consumed renewable energy, continuing to implement electricity-saving measures across 7 categories with 108 items in 2023. Production sites will gradually obtain certification of ISO 46001 Water Efficiency Management Systems and ISO 14046 Water Footprint, to effectively manage water supply-related risks and improve water resource efficiency.

S

We strive to create a work environment that upholds human rights, is dignified, and embraces diversity, equality, and inclusion (DEI), fostering global talent integration.

Winbond places great importance on the development of human rights issues. After completing a human rights due diligence in 2022, the Company continued to optimize and reduce risks in 2023, conducting an Employee Core Values and Engagement Survey in 2023. The survey indicated that over 97% of colleagues are willing to utilize their strengths at Winbond for the next five years.

In addition, we have strengthened the concept of Diversity, Equity, and Inclusion (DEI) and continue to build a more friendly workplace for sustainable talent development. In 2023, a Senior Executive Development Committee was established under the Board of Directors, with staff receiving an average of 50 hours of training per year, continually and systematically cultivating talents. Foreign executives accounted for 17% at the Winbond center, demonstrating the diversity of nationalities in the decision-making circle. We connect the energy of talent cultivation from various colleges, promote the empowerment of the youth, collaborate with National Cheng Kung University to advance the "Semiconductor Course," and sponsored the "Lecture Professor Research Fund" at National Yang Ming Chiao Tung University, leveraging the industry's core capabilities, with concrete actions to construct a technology innovation exchange domain, facilitating the development of the semiconductor industry.

We also continue to lead our employees in contributing to social welfare, creating value, and expanding Winbond's positive social impact. On Family Day, we continue the spirit of public welfare care, providing opportunities for 6,065 colleagues, their families, and 55 students from invited institutions to cultivate an appreciation for arts and culture, rooting cultural experiences.

Winbond is concerned about environmental conservation and ecological preservation. Colleagues actively participate in beach and river cleaning activities, safeguarding the cleanliness of our coastal environment. In 2023, a total of 264 participants joined, collecting 993 kilograms of garbage. Since 2021, Winbond has initiated a tree planting program, planting native tree species in the Kaohsiung Fab area, actively participating in government-led afforestation programs, and supporting the Forestry and Nature Conservation Agency's donations, adoption and tree protection initiatives. Through tripartite cooperation between industry, government, and academia, the Company demonstrates environmental care actions, jointly creating a quality mountain and forest environment.

G

We aim to strengthen the functions of the Board of Directors to enhance the sustainable value of the corporation; and improve and quantify non-financial data and reporting capabilities for better compliance, transparency, and strategic insight.

Winbond strengthens the function of the Board of Directors, elevating the level of sustainable governance. The "ESG Committee" was promoted from an internal management organization to a functional committee under the Board of Directors. The Board of Directors supervises ESG and risk management execution results, demonstrating Winbond's emphasis on sustainable development.

Winbond is keenly aware that research and development are the main driving forces for maintaining competitiveness in the industry. In 2023, Winbond's R&D investments accounted for 23% of its revenue, and the Company was awarded as one of Clarivate's Top 100 Global Innovators for two consecutive years, showcasing Winbond as a semiconductor company committed to pursuing innovation-driven growth and environmental sustainability. In 2023, Winbond formally adopted the "Taiwan Intellectual Property Management System (TIPS)" and obtained A-level certification, nurturing its innovative culture, strengthening awareness of intellectual property protection, and enhancing its sustainable competitive advantage. Facing the post-pandemic digital era, where diverse data ecosystems flourish, Winbond also took the opportunity to upgraded its cybersecurity protection by introducing SEMI-E187 Specification for Cybersecurity of Fab Equipment, establishing a data security management system.

In terms of climate change management, in addition to continuously improving energy use and management through the ISO 50001 Energy Management System, Winbond also set its own goals for the use of renewable energy and net-zero emissions. This includes expanding self-built renewable energy generation facilities, procuring renewable energy through power purchase agreements, and purchasing renewable energy certificates (RECs), all of which are crucial components of achieving net-zero. In response to carbon neutrality requirements from international supply chains and initiatives, we, by purchasing voluntary carbon credits to offset carbon emissions, held a zero-carbon family day for two consecutive years, demonstrating our commitment to sustainable development.

Moreover, we actively follow global sustainability trends by publishing our sustainability report annually and disclosing "Climate-Related Financial Disclosure Report," "UN Sustainable Development Goals Action" and "Materiality Analysis Reports." With an open and transparent approach, we share our progress and achievements with stakeholders, enhancing the transparency of sustainability information disclosure.

About Winbond

Winbond Electronics Corporation ("Winbond") is a global leader in providing semiconductor memory solutions, with a focus on product design, research and development, wafer fabrication, marketing, and after-sales service. Our dedication to delivering comprehensive niche memory solutions has earned us a reputation for excellence among our customers. Our product portfolio includes Specialty DRAM, Mobile DRAM, Code Storage Flash Memory, and TrustME® Secure Memory, which are widely used in various fields such as communication, consumer electronics, industrial and automotive electronics, and computer peripherals. With our headquarters in the Central Taiwan Science Park, and subsidiaries in the United States, Japan, Israel, mainland China, Hong Kong, and Germany, we deliver exceptional service to our customers worldwide. Our two 12-inch wafer fabs, located in the Central and Southern Taiwan Science Parks, are equipped with state-of-the-art technology, allowing us to implement our self-developed process technology and provide our partners with high-quality memory solutions.

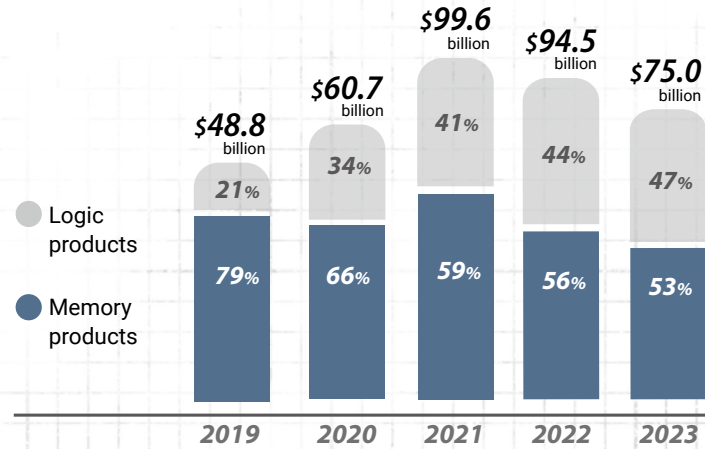
Corporate culture and vision

The corporate culture of Winbond is defined by "business integrity, accountable team work, enthusiasm for learning, aggressive innovation, and contribution to sustainability," which also serves as Winbond's core value, belief, and conduct.

Winbond Culture



Business performance in 2023 (Consolidated Financial Statements)



Revenue	NT\$ 75.0 billion
Corporate governance	Ranked top 6-10% in TWSE Corporate Governance Evaluation
Consolidated net profit after tax	NT\$ 34.0 million

Leading position

Global TOP **1** NOR Flash Supplier

Source: Omdia Research

Solutions










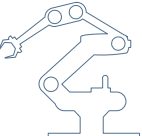






Main products

Code Storage Flash Memory, TrustME® Secure Flash Memory, Specialty DRAM, and Mobile DRAM.

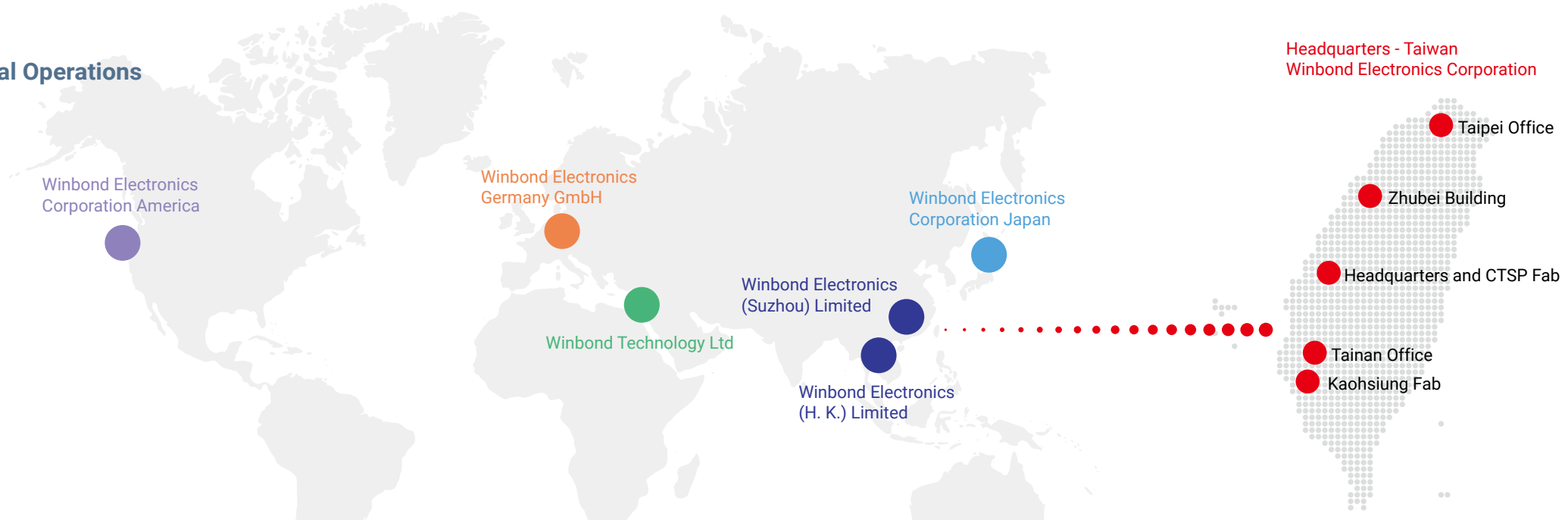
Application

Handheld applications, consumer electronics, computer peripherals, and automotive and industrial-use electronics, which are all fields that have extremely high standards for product quality.

Milestones

<p>1987 Established in Hsinchu Science Park</p> 	<p>2004 Winbond's SpiFlash established the SPI NOR industry standard</p> 	<p>2008 Logic product business spun off as Nuvoton Technology Co. established</p> 	<p>2010 Launched WLCSP (Wafer Level Chip Scale Packaging) for serial NOR</p> 	<p>2014 The SpiStack product line has been launched to bolster data storage capabilities. In addition, Winbond's SPI products feature encoding-based storage, Over-The-Air (OTA) software update applications, and small-form-factor packaging.</p>  	<p>2018 Launched the high-performance QspiNAND to support the automotive industry</p>  	<p>2023 Winbond Group recognized as a Top 100 Global Innovators from Clarivate</p>  
<p>1995 Listed on Taiwan Stock Exchange (TWSE: 2344)</p> 	<p>2006 Launched Multi I/OSpiFlash (Dual 2006, Quad 2007), achieving the highest performance in the industry</p> 	<p>2009 The mass production of the industry's first 16Mb Serial Flash using advanced 90-nanometer technology</p> 	<p>2013 Launched QspiNAND with continuous read, embedded ECC, and bad block management capabilities.</p> 	<p>2017 Introduced the world's first ultra-low voltage 1.2V 8Mb Serial NOR Flash product</p> 	<p>2020 Launched the 1.2V Serial NOR encoded storage flash memory product line</p> 	

Global Operations



Winbond Electronics Corporation America

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Winbond Electronics Corporation Japan

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Miraxia Edge Technology Corporation

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Atfields Manufacturing Technology Corporation

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Headquarters - Taiwan Winbond Electronics Corporation

Headquarters and CTSP Fab
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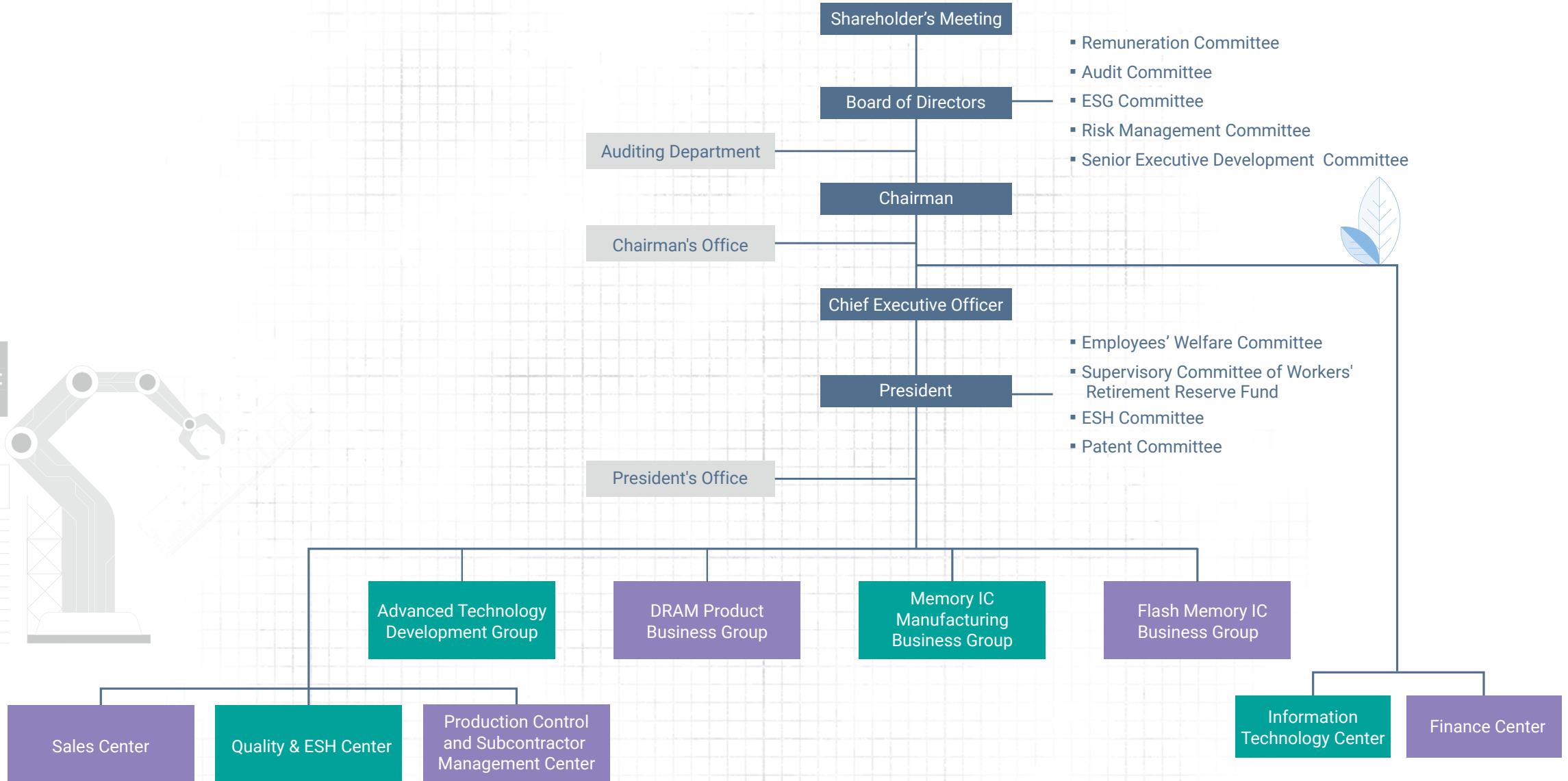
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Winbond Organizational Chart



Our Values

Foresight In Trends, Value in Practice

With a deep understanding of market trends for next-generation products, Winbond continually invests resources in semiconductor design, production technology, and sustainable product innovation. We provide customers with low-carbon and low-power green products, enhancing our competitive advantage and market share in green business opportunities. Also, we continuously improves our ESG performance to enhance Winbond' s sustainable competitiveness.



Design and Development Focus



Products Innovation Advantages

- ✓ Minimize the generation and emissions of hazardous substances in the manufacturing process
- ✓ Shorten manufacturing lead time
- ✓ Reduce manufacturing costs
- ✓ Utilize low-carbon raw materials
- ✓ Enhance product performance
- ✓ Increase product energy efficiency
- ✓ Reduce production energy consumption
- ✓ Achieve smaller size

Technology catalyzes innovation and enhances the quality of life

Applications and Products

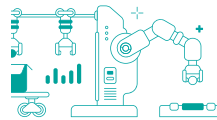


Automotive Electronics

From vehicle body to power systems, to information and entertainment systems, to intelligent driving and advanced safety systems, our technology is used in emerging electric vehicles to achieve a safer, smarter, and more environmentally friendly transportation environment.

- Vehicle-to-Everything (V2X)
- Advanced driver-assistance systems (ADAS)
- Vehicle dashboards
- In-Vehicle Infotainment (IVI)

- Telematics
- Automotive sensing components
- Automotive gateways



Industrial Electronics

For industrial systems, Winbond brings higher performance, information security, and advanced safety in intelligent networking, remote monitoring, human-machine interaction, and on-site machine learning.

- Real-time sales information devices
- Smart factories
- Smart dashboards
- Programmable logic controllers

- Graphical user interfaces
- Industrial gateways
- Industrial machine vision
- Industrial computers

- Unmanned Aerial Vehicles (UAVs)
- Surveillance cameras



5G Communications

With higher data transmission speeds, Winbond provides a foundational platform for the Internet of Things, enabling efficient communication that transcends time and location, enhancing productivity, entertainment, and learning.

- Network digital video converters
- High-speed Ethernet switches
- Wireless terminal access equipment and customer premises equipment (CPE)

- Long-Term Evolution (LTE) technology
- LTE/5G base stations



IoT

In the world of interconnected devices, Winbond accelerates digital transformation while ensuring information security and functional safety, achieving energy efficiency, convenience, and a higher level of safety protection for everyday life.

- Smart cities
- Smart transportation systems

- Self-driving cars
- Smart factories

- Telehealth
- Smart home

- Smart meter



Consumer electronics

For consumer products, Winbond delivers more powerful, energy-efficient, and feature-rich solutions, offering an enhanced product experience.

- Smartphones
- Smartwatches
- AR smart glasses

- Tablet computers
- Smart TV
- Smart home

- Satellite navigation
- Digital cameras
- True wireless earphones

- Set-top boxes

Awards and Recognition



Sustainability Recognition

 <p>Taiwan Corporate Sustainability Award</p> <ul style="list-style-type: none"> Taiwan Top 100 Sustainable Corporate Award Corporate Sustainability Report Award – Platinum Level Talent Development Leadership Award Human Rights Leadership Award Workplace Wellbeing Leadership Award Innovation and Growth Leadership Award 	 <p>Taichung City Government</p> <ul style="list-style-type: none"> Taichung City Government 5th Taichung Low Carbon Sustainable City Outstanding Contribution Award 	 <p>British Standard Institution (BSI)</p> <ul style="list-style-type: none"> 2023 BSI Sustainable Resilience Excellence Award
 <p>Selected FTSE4Good</p> <ul style="list-style-type: none"> Selected as a constituent company of FTSE4Good emerging index 	 <p>Responsible Business Alliance (RBA)</p> <ul style="list-style-type: none"> Platinum, VAP (Validated Assessment Program) 	 <p>1111 Job Bank</p> <ul style="list-style-type: none"> Gold Level Award 2023 Happy Enterprise
	 <p>ECOVADIS 2023 Sustainability Rating</p> <ul style="list-style-type: none"> Silver 	 <p>National Taxation Bureau of the Central Area, Ministry of Finance</p> <ul style="list-style-type: none"> Awarded as an outstanding business entity for using electronic uniform invoices
	 <p>CDP</p> <ul style="list-style-type: none"> Climate change: B Water security: B 	

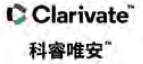





Corporate Governance

 <p>TWSE The 10th Corporate Governance Evaluation</p> <ul style="list-style-type: none"> Ranked in the top 6% to 20% among listed companies
 <p>Taiwan Index Plus Selected as a constituent company of</p> <ul style="list-style-type: none"> TWSE Corporate Governance 100 Index TWSE RAFI® Taiwan High Compensation 100 Index TWSE RA Taiwan Employment Creation 99 Index
 <p>Taiwan Institute of Directors</p> <ul style="list-style-type: none"> 2023 Taiwan Best-in-Class 100





Product Innovation

 <p>Clarivate</p> <ul style="list-style-type: none"> Top 100 Global Innovators 	 <p>Industrial Development Administration, MOEA</p> <ul style="list-style-type: none"> TIPS A-level certification
 <p>Intellectual Property Office, MOEA (TIPO)</p> <p>Top 100 Patent Applicants in 2023:</p> <ul style="list-style-type: none"> 23th Place among the Applicants of the Taiwanese Juridical Persons 23th Place among the Patentees of the Taiwanese Juridical Persons 	 <p>Taiwan Continuous Improvement Awards</p> <ul style="list-style-type: none"> 2 Golden Tower Awards 1 Silver Tower Award



International Standards Compliance and Verification

<ul style="list-style-type: none"> ISO9001 Quality Management System IATF 16949 Automotive Quality Management System Standard QC 080000 Hazardous Substance Process Management System ISO/SAE 21434 Road vehicles – Cybersecurity engineering ISO 26262 Road vehicles - Functional Safety ISO 27001 Information technology – Security techniques – Information security management systems – Requirements ISO 14001 Environmental Management System ISO 14064-1 Greenhouse Gases – Part 1 ISO 14067 Products Carbon Footprint 	<ul style="list-style-type: none"> ISO 45001 Occupational Health and Safety Management System ISO 50001 Energy Management System ISO 46001 Water Efficiency Management Systems ISO 14046 Water Footprint <div data-bbox="1996 1340 2460 1508">  <p>Product and Service Quality Management</p>  </div>
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Sustainable Performance

E Environmental



2.28 M tCO₂e reduction (accumulated)

Since 2006, Winbond has participated in PFCs emission reduction projects with the Taiwan Semiconductor Industry Association (TSIA) and the World Semiconductor Council (WSC), achieving a total reduction of approximately 2.28 million tCO₂e, equivalent to the annual carbon sequestration of 5,907 Daan Forest Parks.



Nature-based solutions removed 1,380 tCO₂e

Winbond implemented nature-based solutions, removing 1,380 tCO₂e over 30 years through afforestation and carbon sequestration.



456 GWh electricity saved

From 2019 to 2023, Winbond saved a cumulative total of 456 GWh of electricity, equivalent to the annual consumption of 130,233 households.



2.1 M kWh of renewable energy procurement

Winbond procured approximately 2.1 million kWh of renewable energy in 2023.



Fab-wide water recovery rate reached 82.2%

Our Fabs recycled a total of 13.15 million cubic meters of water, resulting in a water recovery rate of 82.2% across the entire facility.



Water Conservation of 4,000 megaliters

Cumulative water conservation of 4,000 megaliters from 2019 to 2023.



ISO 46001 and ISO 14046

Winbond implemented ISO 46001 water efficiency and ISO 14046 water footprint management systems.



Waste recycling rate 90.9%

13,595 metric tons of waste were recycled, resulting in a recycling rate of 90.9%.



Removal rate for VOCs in 2023 reached 98%

The average removal rate for volatile organic compound was 98%.

S Social



Human rights due diligence

In 2023, Winbond issued its first independent report on human rights due diligence.



Diversity and Inclusion

- 17% of senior executives are foreign nationals.
- In Taiwan, women make up 43% of new hires at Winbond.
- The weighted number of employees with disabilities increased by 19%.



Childcare Subsidies Exceeds NT\$330M

Winbond has distributed NT\$330 million in monthly childcare subsidies of NT\$6,000 to its employees from 2011 to 2023.



Social Welfare Investment Reaches NT\$18.11M

Total investment in social welfare reached NT\$18.11 million in 2023.



Conserving and breeding 27 species of Theaceae plants, we safeguard Taiwan's native flora

Among the 42 Theaceae species found throughout Taiwan, efforts have been made to cultivate 27 varieties. Of these, 1 species is critically endangered, 1 is endangered, 6 are vulnerable, and 3 are near threatened.



Cultural Tour Sponsorship NT\$7.29M

In 2023, Winbond sponsored a cultural tour for 6,120 people at the National Palace Museum Southern Branch, costing NT\$7.29 million.



Boosted **human capital** through an average of 50 training hours per employee, resulting in a 19% increase in staff training compared to 2022.



The average salary of non-supervisors was NT\$ 1.59M

The average salary of non-supervisory full-time employees in 2023 was NT\$1.59 million.

G Governance



The Board oversees the ESG Committee

The ESG Committee, composed of the Chairman and all independent directors, guides the direction of Winbond's sustainable development strategy.



Senior Executive Development Committee established

Strengthening succession teams to ensure sustainable business operations and foster talent development.



NT\$955M renewable energy investment plan

Winbond accumulatively invested in renewable energy development and continuously collaborated with green industry supply chain alliances from 2022 to 2023.



A pioneer in joining in Taiwan Carbon Exchange

Winbond became a representative of international enterprises making inaugural carbon credit purchases.



Acquisition of 13,500 tCO₂e of carbon credits

Since 2022, a cumulative acquisition of voluntary carbon credit projects from 9 countries in Asia and Africa, creating diverse sustainable benefits.



Clarivate global top 100 innovators

Selected for two consecutive years, 2023-2024.



SEMI-E187 enhances cybersecurity defense in semiconductor manufacturing

The introduction of SEMI-E187, a cybersecurity standard for semiconductor equipment, strengthens cybersecurity defense in semiconductor manufacturing.



Winbond awarded TIPS A certification

Winbond received the Taiwan Intellectual Property Management Specification (TIPS) A-level certification.